Method and Device for Permanent Bonding

Abstract

This invention relates to a method for permanent bonding of a first layer (2) of a first substrate (1) to a second layer (2') of a second substrate (1') on a bond interface (5), characterized in that a dislocation density of a dislocation (4) of the first and/or second layer (2, 2') is increased at least in the region of the bond interface (5) before and/or during the bonding.

Furthermore this invention relates to a corresponding device.

Figure 2a in this respect